

GENE-9655

Thermal Image Analysis Report

Report NO: 10E080004

Sample Configuration & Quantity Under Test

- CPU Board: GENE-9655 Rev.A0.3
- Carrier Board:N/A
- CPU: Intel® Celeron® Processor 550
- Memory: Transcend DDR2 SO-DIMM 667 1GB
- HDD: WD(Western Digital) 2.5 SATA H.D 80GB - WD800BEVS
- BIOS : GENE-9655 BIOS Rev 1.0 (3/10/2010)
- Test Software: Windows XP sp3 / Run Prime95 v25.11
- ATX Power Supply: Delta 350W GPS-350EB-102A(Short PS-ON and GND to simulate AT mode)
- Cooler:



Test Result Summary

- Pass
 Fail
 Pass with Deviation

Comment: Please refer to U12010/03/26

Issue Stamp

Jansin Lee

Manager

Allen Hsu

Test Engineer

Thermal Image Analysis

1. Test Date: 03/25/2010

2. Test Product: GENE-9655

3. Test Site: AAEON QA Internal Lab.

4. Temperature Measurement:

1. GRAPHTEC midi LOGGER TYPE - GL200

2. IR Scanner: Infrared Camera

NIPPON AVIONICS CO., LTD.

Model: TVS-100

Date of Calibration: 09/17/09

Serial Number: 0179L2746

5. Test Condition:

Component Side-1 (Test by TVS-100 & TH-046): 25.3 °C With cooler

Component Side-2 (Test by TVS-100): 25.2 °C With cooler

6. Test Software:

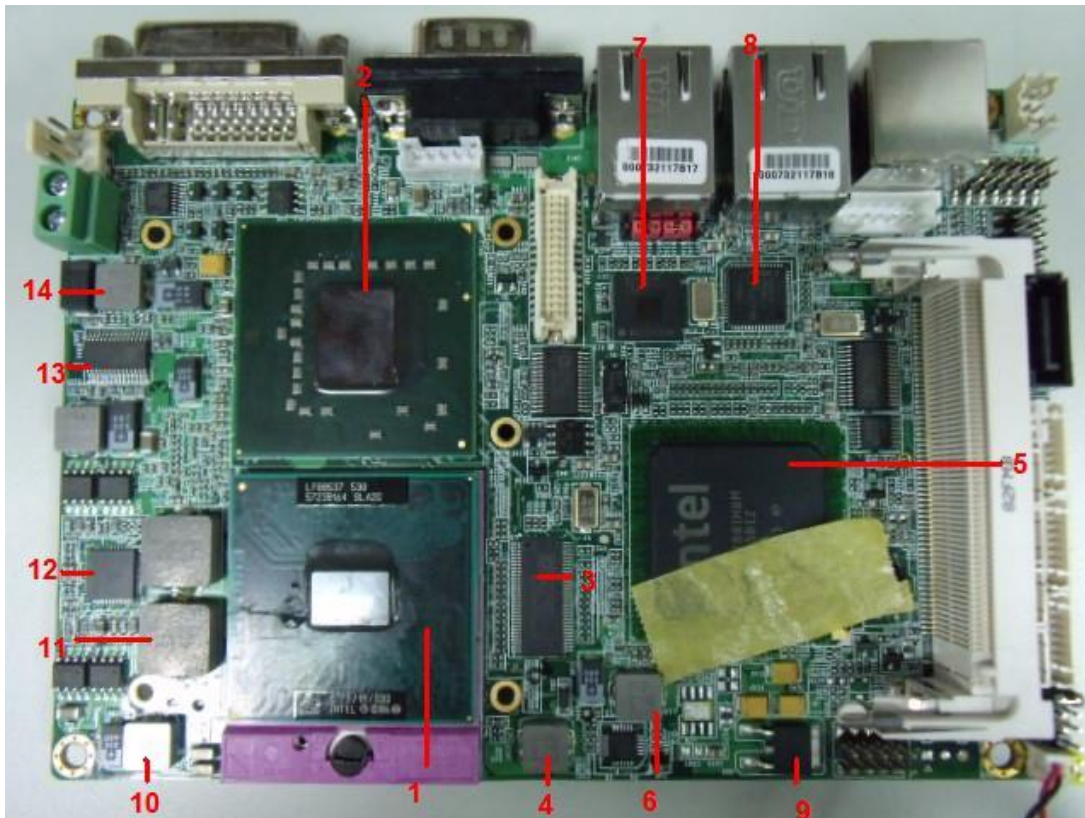
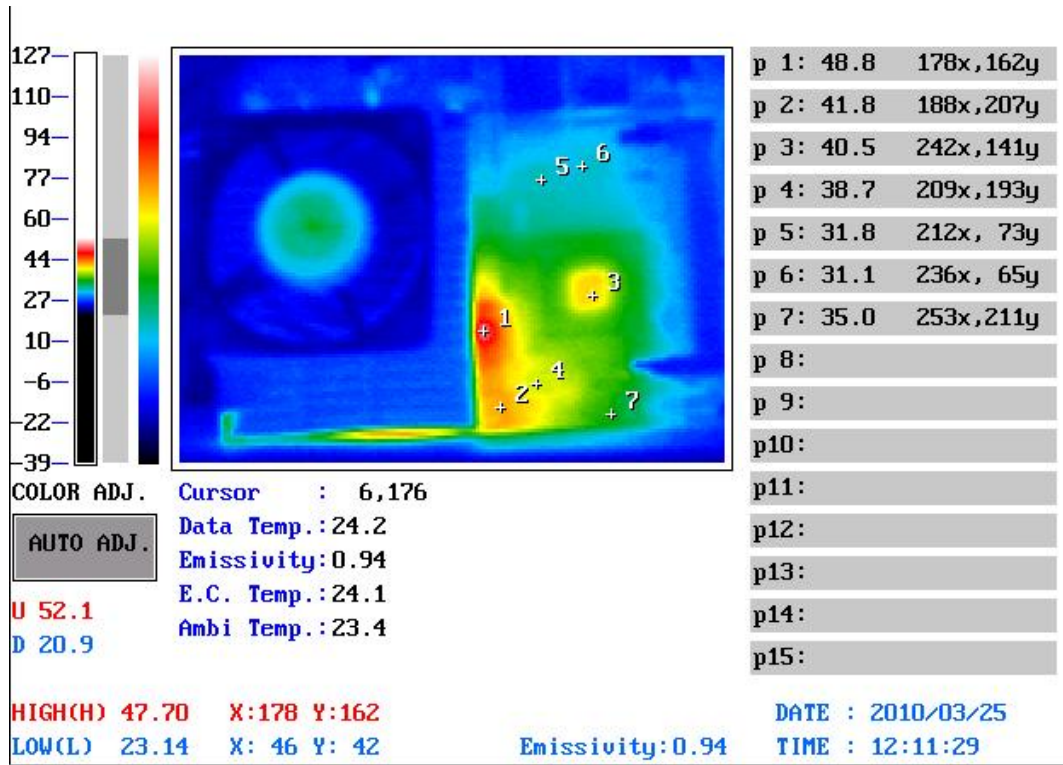
Windows XP sp3 / Run Prime 95 v25.11

7. Take Picture Time:

After power on 2 hours

Temperature Profile Test:

Component Side-1:



Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.3°C	60°C	
1	U1(CPU)	Intel® Celeron® Processor 550 (1M Cache, 2.00 GHz, 533 MHz FSB)	100	62.1	96.8(*3)	GL200 measur ed
2	U2	(TF)IC.SMD.FCBGA1299Pin.Chipset.Intel.LE82GME965.SL A9F.;EE-A071936;14S4296501;TWN	105(Td)	40.6	75.3	
3	U5	(TF)IC.SMD.TSSOP64P.CLOCKGENERATOR.ICS.ICS9LP5 05-1HGLFT;EE-A071253;14S3950500;TWN	100	48.8	83.5	
4	L14	(TF)COIL.1uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=9mohm.Ir ms=11Amp.GOTREND.GSTC063P-1R0MN;EE-A061520;1211 000180;TWN	125	41.8	76.5	
5	U3	(TF)IC.SMD.ChipsetICH8M.INTEL.NH82801HBM.SLB9A;E E-A081571;14S4280121;TWN	----	40.5	75.2	
6	L13	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28mohm.Irms=6 Amp.GOTREND.GSTC063P-3R3MN;EE-A061509;121110336 L;TWN	125	38.7	73.4	
7	U11	(TF)IC.SMD.BGA81P.GigaBitEthernetChipset.INTEL.RU825 66MM;EE-A080233;14S4256610;TWN	125	31.8	66.5	
8	U9	(TF)IC.SMD.QFN64P.PCI-EGigaBitEthernetChipset.Intel.WG 82574L SLBA8;EE-A081303;14S4825740;TWN	109	31.1	65.8	
9	Q58	(TF)PWR.SMD.TO-252.N-Channel Power 25V 60A MOSFET.APEC.AP70T03GH;EE-A031083;1315700310;TWN	150	35.0	69.7	
10	L15	(TF)COIL.2.2uH.SMD.7.3*6.8*3.0mm.+/-20%.DCR=18mohm. Irms=8Amp.GOTREND.GSTC063P-2R2MN;EE-A081766;121 110226C;TWN	125	39.1	73.8	GL200 measur ed
11	L10	(TF)COIL.0.56uH.Irms=25A.Isat=40A.20%.SMD(11.5x10.3x4. 0).2pin.RDC=1.8mOhm.GOTREND.GSTC104P-R56MN;EE-A 061714;1211105673;TWN	125	46.6	81.3	
12	U32	(TF)IC.SMD.QFN48P.IMVP6TwoPhasePWM.Intersil.ISL6262 ACRZ-T;EE-A081065;14S3626201;TWN	100	54.9	89.6	
13	U39	(TF)IC.SMD.eTSSOP-28.DualSynchronousController.NS.LM5 642XMH;EE-A091655;14S1564201;TWN	100	38.6	73.3	
14	L12	(TF)COIL.3.3uH.SMD.7.3*6.8*3.0mm.DCR=28mohm.Irms=6 Amp.GOTREND.GSTC063P-3R3MN;EE-A061509;121110336 L;TWN	125	38.5	73.2	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:**

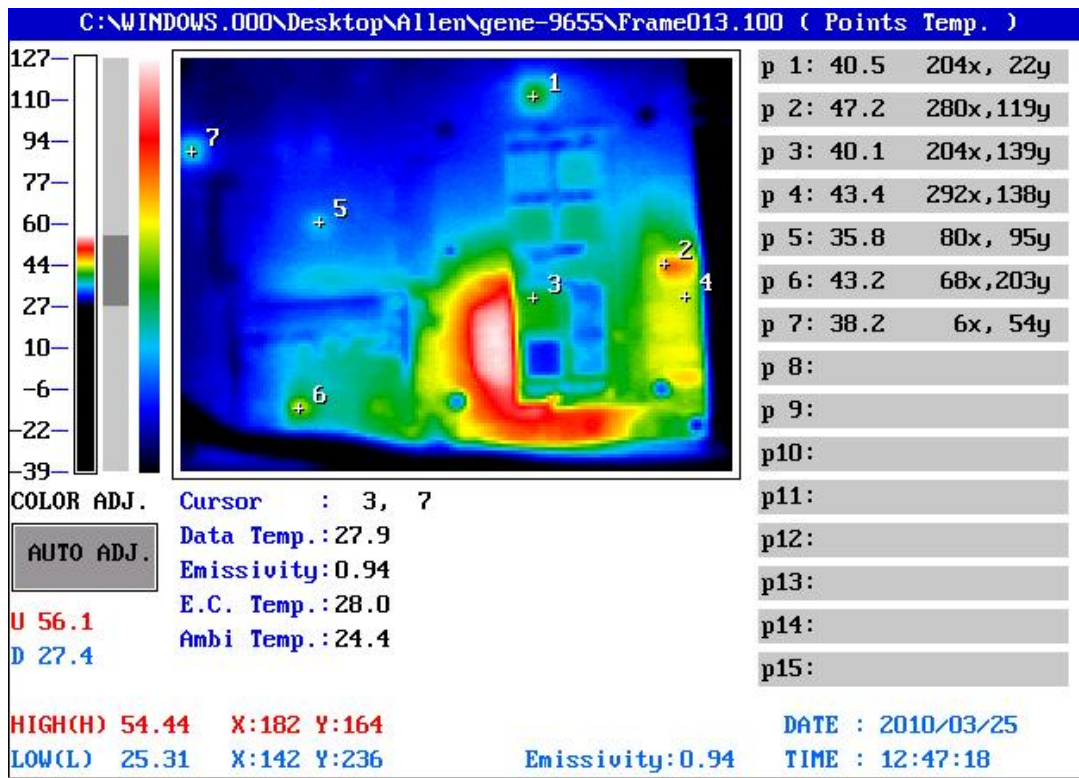
- **Fail** : Tm > Tc+5°C; The measured value is over specification plus margin.

- **Margin** : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.

For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.

- **Pass** : Tm < Tc-10°C; The measured value is with safety margin.

Component Side-2:



Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.2°C	60°C	
15	U8	(TF)IC.SMDLQFP.48P.DVITransmitter.CHRONTEL.CH7307C-DEF;EE-A050797;14S4730701;TWN	125	40.5	75.3	
16	U37	(TF)PWR.SMD.SOP8.30V.11A.SingleN-ChannelFAIRCHILD.FDS6690A;EE-A071202;1315669000;TWN	125	47.2	82.0	
17	DIMM1(RAM)	Transcend DDR2 SO-DIMM 667 1GB - TQ123EJF6 T0743	85	40.1	74.9	
18	U29	(TF)PWR.SMDSO8.N-ChannelMOSFET30V15A.FAIRCHILD.FDS8896;EE-A070070;1315889611;TWN	125	43.4	78.2	
19	U13	(TF)IC.SMD.QFP128P.SuperI/Ow/4COMs.ITE.IT8781F/AX-L;EE-A081754;14S4878100;TWN	100	35.8	70.6	
20	U44	(TF)PWR.SMD.SO-8P.P-ChannelMOSFET.APEC.AP6679GM-HF;EE-A071268;1315667910;TWN	125	43.2	78.0	
21	U12	(TF)IC.SMD.LQFP 48P.7.1+2 Channel High Definition.Audio Codec.REALTEK.ALC888-GR;EE-A071056;14S3088800;TWN	100	38.2	73.0	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.